PREDICTABLE DESIGNS

9 ESP32 DESIGN MISTAKES

THAT SABOTAGE YOUR PRODUCT

MISTAKE 1: CHOOSING THE WRONG ESP32 VARIANT

- Map out product needs before selecting a variant (Wi-Fi, Bluetooth, GPIOs, RAM, Flash, peripherals).
- Avoid defaulting to the most powerful or cheapest option.
- Check lifecycle status and availability before committing.
- Choose a variant with enough headroom, but without unnecessary overhead.

MISTAKE 2: NOT OPTIMIZING POWER CONSUMPTION

- Use deep sleep modes whenever possible.
- Disable Wi-Fi and Bluetooth when not needed.
- Define duty cycle and select low-power components early in design.
- Measure current draw in both active and sleep modes.
- Consider single-core variants for lower power needs.

MISTAKE 3: USING BARE CHIPS INSTEAD OF CERTIFIED MODULES

- Prefer certified modules unless producing hundreds of thousands of units.
- Avoid full RF layout and certification burden without in-house expertise.
- Certified modules reduce risk, speed time-to-market, and simplify compliance.

MISTAKE 4: BAD ANTENNA PLACEMENT OR DESIGN

- Follow Espressif's antenna placement guidelines.
- Keep antenna near board edge with clear keep-out zone (no copper/ground nearby).
- Avoid placing antennas near batteries, shields, or enclosure walls.
- Test final board inside enclosure to confirm wireless performance.

MISTAKE 5: IGNORING HEAT DISSIPATION

- Add copper pour and thermal vias under module to spread heat.
- Increase board thickness or use a heatsink if needed.
- Add venting or airflow in enclosure for high-power use.
- Perform thermal testing in real conditions early in development.

MISTAKE 6: POOR POWER SUPPLY DESIGN

- Use a regulator with fast transient response to handle Wi-Fi/Bluetooth spikes.
- Add bulk capacitors close to ESP32 for current smoothing.
- Test under real-world peak loads and wake-up transitions.

MISTAKE 7: DESIGNING WITHOUT OTA UPDATE CAPABILITY

- Set up flash partitions for OTA updates.
- Test OTA process thoroughly, including recovery from failed updates.
- Implement OTA early to ensure long-term product flexibility.

MISTAKE 8: NOT TESTING IN THE REAL WORLD EARLY ENOUGH

- Test inside the final enclosure with full firmware.
- Run extended stress tests (heat, cold, drained batteries, interference).
- Test for days, not just minutes, to catch rare issues like memory leaks or resets.

MISTAKE 9: WRONG GPIO USAGE

- Identify fixed-function pins first (ADC, touch, flash, strapping).
- Assign critical interfaces (SPI, I2C, UART) before general tasks.
- Avoid using restricted pins for LEDs or other low-priority signals.
- Consider routing distance and package when assigning GPIOs.

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Meet your guide: John Teel

Hey there, I'm a former microchip design engineer at Texas Instruments and founder of a hardware startup that sold products in hundreds of retail stores. My chip designs are in devices from Apple, Intel, and more.

Now, my full-time focus is helping people like you bring new electronic products to life, without wasting time, money, or risking everything.

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